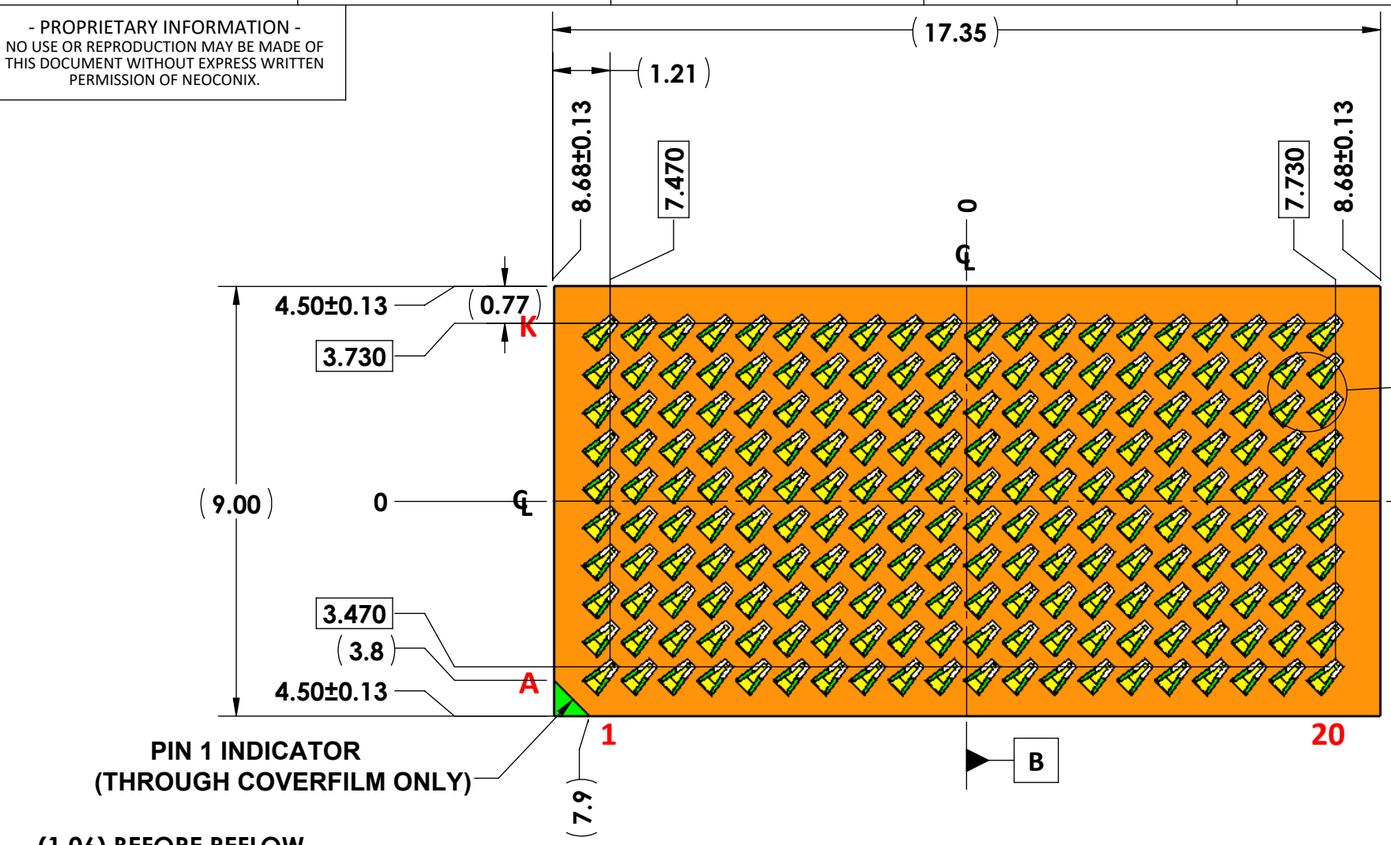
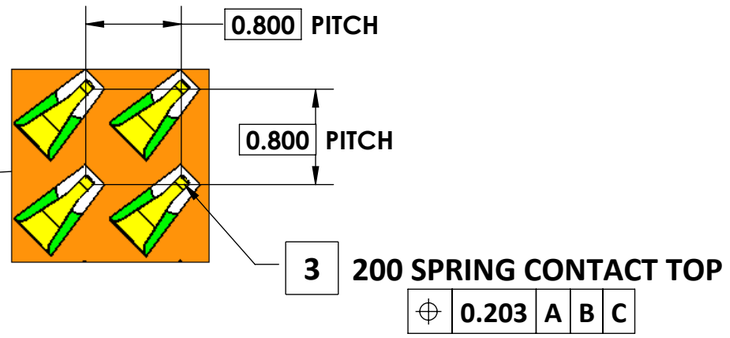
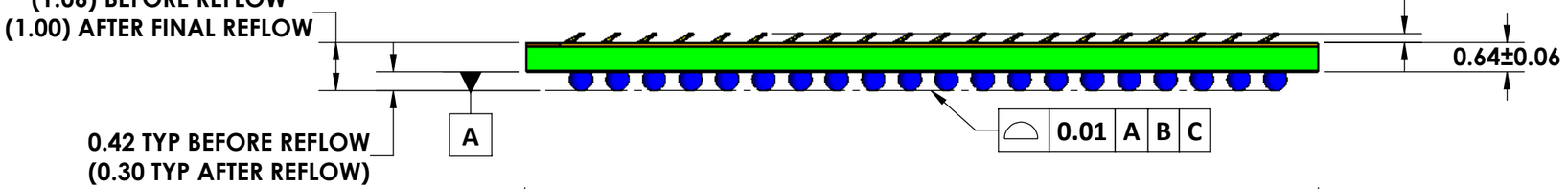
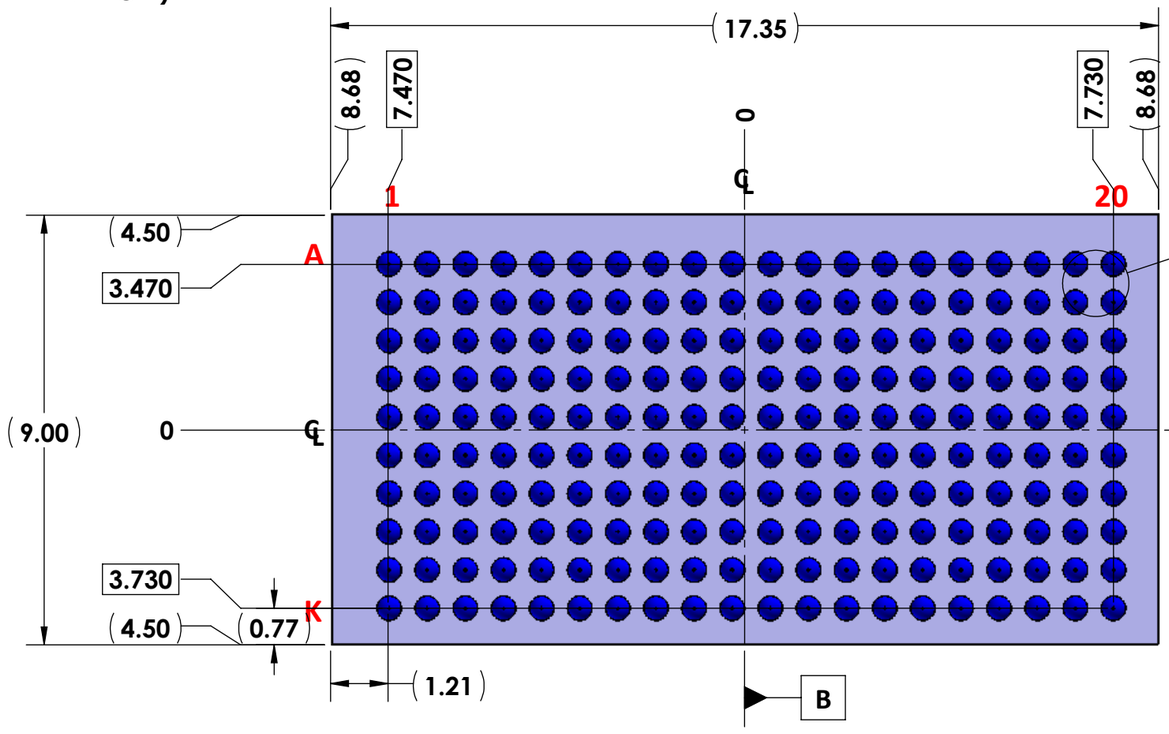
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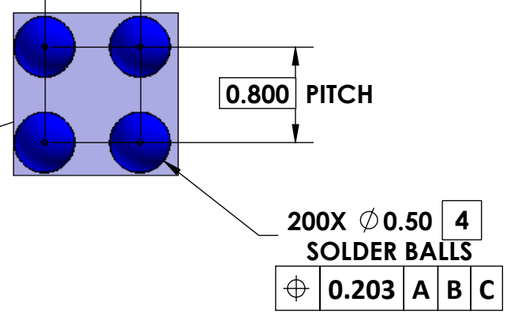
REVISIONS				
REV	ECO	DESCRIPTION	DATE	DRAWN BY
1	0000	INITIAL RELEASE	10-01-2026	TAN











NOTES (UNLESS OTHERWISE SPECIFIED):

1. INTERPRET DRAWING PER ASME Y14.5-2018.
2. COMPLIANT WITH RoHS DIRECTIVE 2011/65/EU AND REACH.
3. CENTER MARKS OF CONTACT POSITIONS ARE FOR COMPRESSED STATE.
4. LEAD-FREE SOLDERBALLS.

REF: Z-RAY P/N ZA8-20-1-1.00-Z-10-2

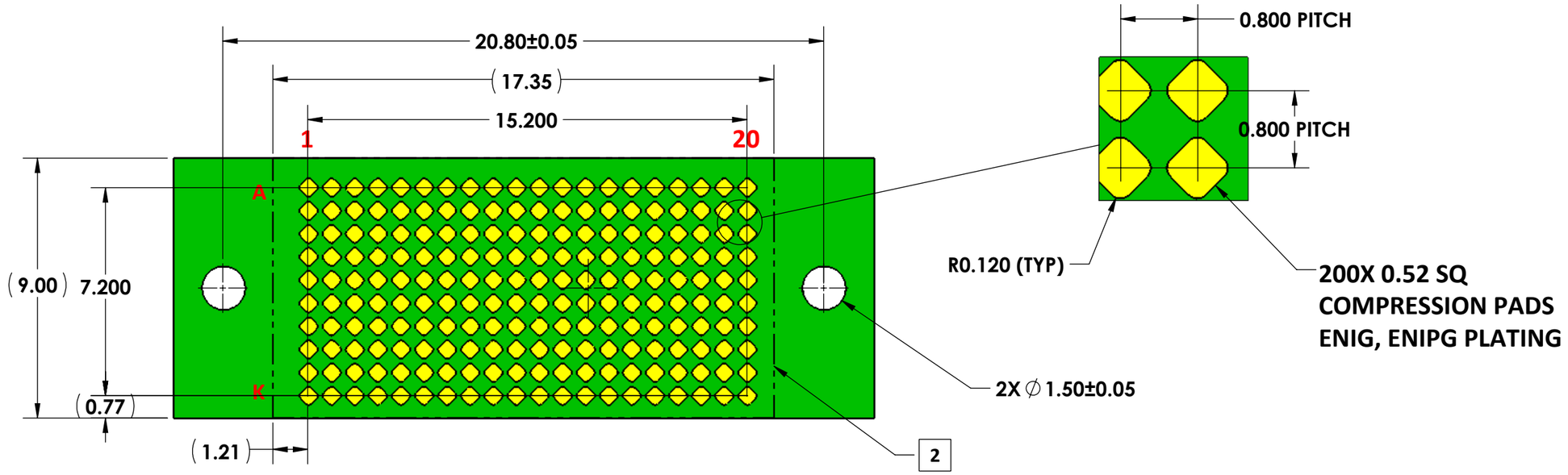
neoconix
4020 MOORPARK AVE. #108
SAN JOSE, CA 95117 USA
TEL: 408-530-9393 FAX: 408-530-9383

DIMENSIONS ARE IN MM [INCH]
.X ± 0.13 [.005]
.XX ± 0.08 [.003]
.XXX ± 0.025 [.001]
ANGLE: NO DEC ±2 DEGREE
.X ±
.XX ±
THIRD ANGLE

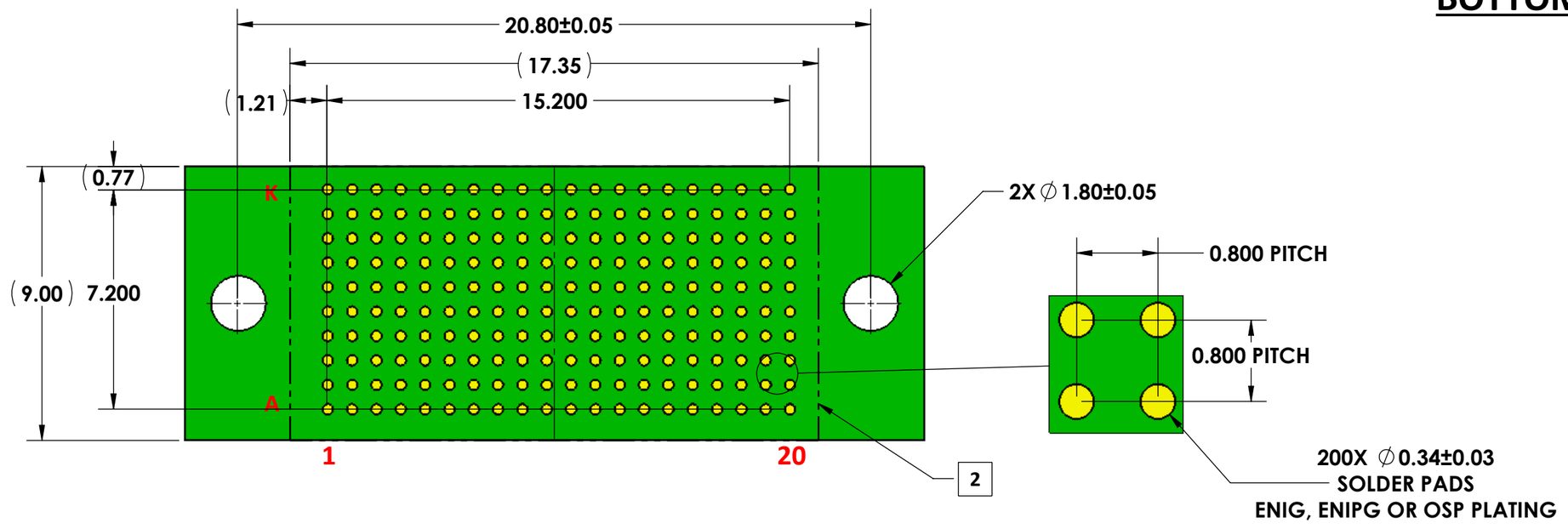
MATERIAL: SEE NOTES		TITLE: 200 POSITIONS INTERPOSER LGA-BGA PCBEAM (0.8mm PITCH)
FINISH: SEE NOTES		
DRAWN BY: TAN NGUYEN	10-01-2026	
CHECKED BY:		SIZE: B+ / DWG NUMBER: SPZ-C200BA / REV: 1
ENGR APPR:		
MFG APPR:		
QA APPR:		SCALE: 5:1 / SHEET 1 OF 2

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TOP PCB FOOTPRINT



BOTTOM PCB FOOTPRINT



NOTES: UNLESS OTHERWISE SPECIFIED:

1. **VIAS IN PAD AREA MUST BE FILLED, PLATED AND PLANARIZED WITH 25UM MAX DIMPLE.**
2. **INTERPOSER OUTLINE; NO COMPONENTS ALLOWED WITHIN THIS AREA.**
3. **IF SOLDERMASK IS APPLIED IN THE ARRAY AREA IT SHALL NOT PROTRUDE ABOVE THE PLANE OF THE CONTACT PAD SURFACE.**

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DIMENSIONS ARE IN MM [INCH]
.X ± 0.13 [.005]
.XX ± 0.08 [.003]
.XXX ± 0.025 [.001]
ANGLE: NO DEC ±2 DEGREE
.X ±
.XX ±
THIRD ANGLE

MATERIAL: SEE NOTES	
FINISH: SEE NOTES	
DRAWN BY: TAN NGUYEN	10-01-2026
CHECKED BY:	
ENGR APPR:	
MFG APPR:	
QA APPR:	

TITLE: RECOMMEND PCB FOOTPRINT
SIZE: B+
DWG NUMBER: SPZ-C200BA-PCB
REV: 1
SCALE: 2:1
SHEET 2 OF 2